CEI Modular Featuring Cooled-by-ZutaCore

to Densify Data Centers, Lower Costs and Reduce Complexity

CEI Modular designs, integrates, deploys and commissions solutions with data center operator needs in mind. As high-performance computing cooling demands increase and air solutions reach their limit, operators are struggling with effective cooling solutions that do not involve water, which could lead to risk of IT meltdown. CEI Modular exists to solve these kinds of challenges. Leveraging extensive insight to anticipate problems and plan for the entire product life cycle, CEI Modular vets technologies, then designs, builds, tests and delivers high-quality, complete solutions.

By incorporating ZutaCore's direct-on-chip, two-phase, waterless liquid cooling solution into its modular data center designs, CEI Modular is revolutionizing the data center. With the HyperCool2™ inside, CEI Modular is shrinking the data center footprint up to 40 percent, simplifying design, streamlining installation and densifying computing. ZutaCore's liquid cooling solution is the latest technology in CEI Modular's portfolio of modular data center designs.

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ZutaCore's HyperCool2™

provide the most innovative

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technology along with a flexible,

cost-effective alternative to

traditional data center construction.

Pre-designed to match emerging

business needs, pre-tested to work every

time and built in a controlled environment

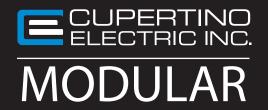
to ensure the highest quality, the result is a CEI

Modular data center with the same performance

and reliability as stick built, but with faster delivery and

minimized risk for quicker revenue generation.







For more information about CEI Modular cooled-by-ZutaCore solutions, please contact us at modular@cei.com.

Solution Overview

- ZutaCore HyperCool2™ system offered by industry leader CEI Modular
- Partnership with trusted modular and manufacturing partner

Your Modular Data Center Solution For

- Direct-on-chip cooling to alleviate cooling boundaries
- On demand liquid cooling with a safe, non-conductive refrigerant

Benefits

- Unparalleled heat dissipation with no risk of IT meltdown
- Triple computing densities on one-third of the footprint